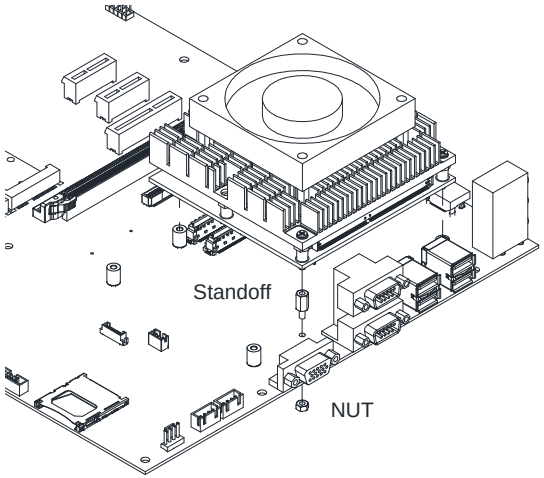
Note: ***When installing CEM130 on CEB94011, please add stand-off and secure with nut. Then, use the screws to secure the heatsink plate to the CEM130.***



Quick Start

The basic procedures required to power on CEM130:

(1). Make sure the power is OFF before connecting the CEM130.
(2). Check to ensure the onboard switch SW1-1 and SW1-2 are set to default (OFF position).
(3). Firmly install DDR4 SO-DIMM in SDIMM1 (on bottom side of the board)/DIMM1 (on top side of the board) until fully seated. For single memory channel configuration, install memory module in channel 0 (SDIMM1) DDR4 SO-DIMM socket. For dual memory channel configuration, install memory modules of the same size, chip width, density and rank in both channel 0 (SDIMM1) and channel 1 (DIMM1) DDR4 SO-DIMM sockets.
(4). Attach heatsink to the CEM130, refer to section Installing Thermal Solution.
(5). Install the CEM130 onto the suggested COM Express™ baseboard, CEB94011.
(6). Properly install all necessary peripheral devices such as hard disk, display, keyboard and etc. to the baseboard.
(7). Firmly attach power supply to the baseboard power connector.
(8). Turn on the system power.
(9). Press power button on the baseboard to start CEM130.

9418D130000E

Version A1 February 2020
Printed in Taiwan

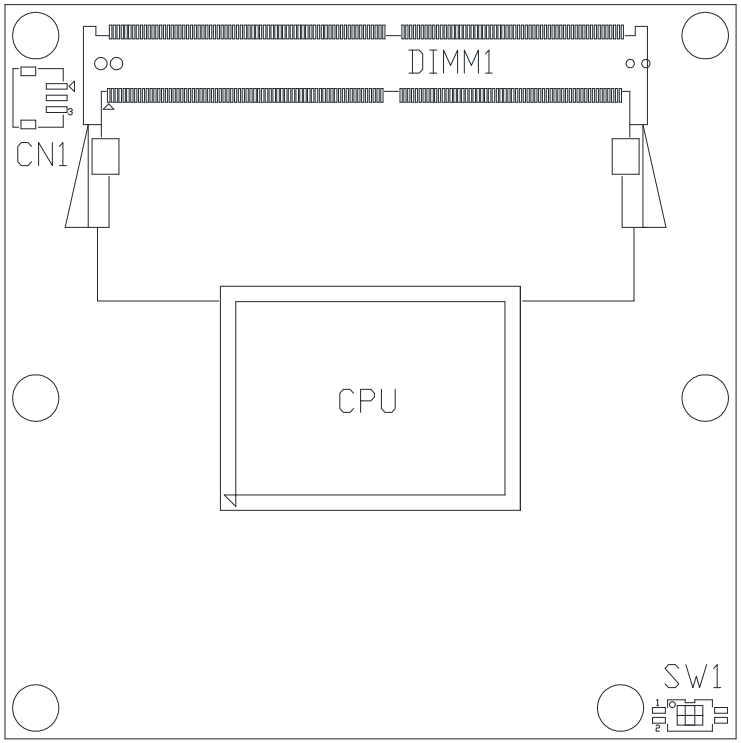
CEM130 Quick Installation Guide

Checklist

✓ CEM130 Board x1

Note: ***Please contact your local vendors if any damaged or missing items. DO NOT apply power to the board if there is any damaged component.***

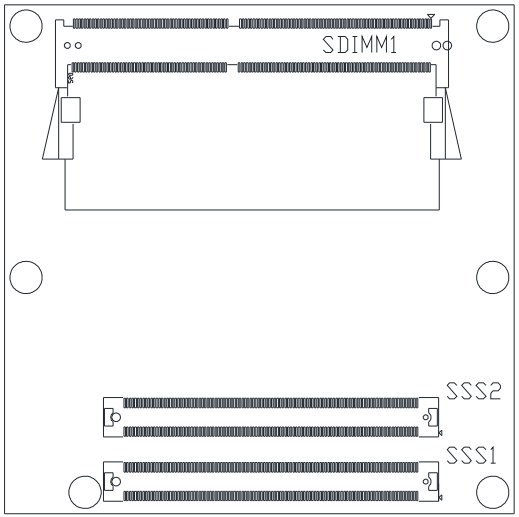
Module Layout



Top View

9418D130000E

Version A1 February 2020
Printed in Taiwan



Bottom View

Switch Settings

Before applying power to the CEM130, please make sure onboard switches are in factory default positions.

Switch	Description	Setting
SW1	Auto Power On Default: Disable	SW1-1 OFF
	Restore BIOS Optimal Defaults Default: Normal Operation	SW1-2 OFF

Connector

Connector	Description
CN1	Fan Connector
SSS1	COM Express™ Connector
SSS2	COM Express™ Connector
SDIMM1	Channel 0 DDR4 SO-DIMM Socket
DIMM1	Channel 1 DDR4 SO-DIMM Socket

9418D130000E

Version A1 February 2020
Printed in Taiwan

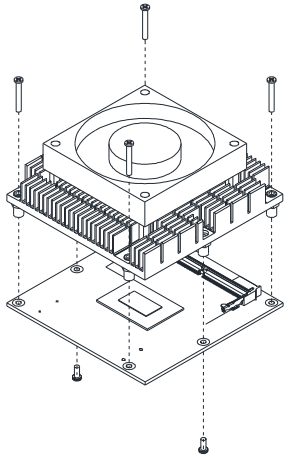
Installing Thermal Solution

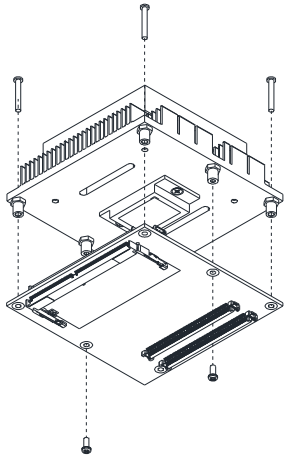
For thermal dissipation, a thermal solution enables the CEM130's components to dissipate heat efficiently. All heat generating components are thermally conducted to the heatsink in order to avoid hot spots. Figure below illustrates how to install the thermal solution on CEM130.

1. There is a protective plastic covering on the thermal pads. This must be removed before the heatsink can be mounted.

2. Each heatsink is designed for a specific CEM module. The thermal pads on the heatsink are designed to make contact with the necessary components on the CEM module. When mounting the heatsink you must make sure that the thermal pads on the heatsink make complete contact (no space between thermal pad and component) with the corresponding components on the CEM module. This is especially critical for CEM modules that have higher CPU speeds (for example 1.46GHz or more) to ensure that the heatsink acts as a proper thermal interface for cooling solutions.

3. Before installing the heatsink to the CPU module, please apply thermal grease on the CPU die. This CPU module has assembly holes for installing heatsink plate. Use the appropriate screws to secure the heatsink plate to the CEM130. Be careful not to over-tighten the screws.





9418D130000E

Version A1 February 2020
Printed in Taiwan